



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	24-11-2022
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H725IEK6	E4MR*483XXXZ	C	9991	24-11-2022
	Amount	UoM	Unit type	ST ECOPACK Grade
	111.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SN96.5 AG3.5%	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10	201	bulk solder	
Comment	Package : AOE7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E4MR*483XXXZ				6000000.0	1000000.3
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.738	mg	supplier	die	Silicon (Si)	7440-21-3		2.238	mg	817385	20162
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	21549	532
				supplier	metallization	Copper (Cu)	7440-50-8		0.186	mg	67933	1676
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	365	9
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	10957	270
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	1826	45
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	365	9
				supplier	Passivation	Silicon Oxide	7631-86-9		0.218	mg	79620	1964
				supplier	BT-substrate	Thermosetting resin (Including filler)	Not Applicable		4.531	mg	110010	40817
				supplier	BT-substrate	Glass cloth	65997-17-3		11.120	mg	270000	100177
Substrate A26935-0	M-011 Other inorganic materials	41.184	mg	supplier	BT-substrate	Copper foil	7440-50-8		10.186	mg	247340	91770
				supplier	Solder mask	3-methoxy-3-methylbutyl acetate	103429-90-9		7.476	mg	181530	67353
				supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		1.913	mg	46450	17234
				supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6		0.474	mg	11500	4267
				supplier	Solder mask	Morpholine derivative	Trade Secret		0.494	mg	12000	4452
				supplier	Solder mask	Napthalene (Carc. Cat. 3,R40)	91-20-3		0.048	mg	1170	434
				supplier	Solder mask	Barium Sulfate	7727-43-7		4.942	mg	120000	44523
				supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-term	68610-41-3		2.600	mg	650000	23423
				supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.964	mg	241000	8685
				supplier	Glue or tape	Dapsone	80-08-0		0.096	mg	24000	865
Glue ATB-125	M-011 Other inorganic materials	4.000	mg	supplier	Glue or tape	Siloxanes and Silicones, di-Me, reaction produc	67762-90-7		0.100	mg	25000	901
				supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	Proprietary		0.080	mg	20000	721
				supplier	Glue or tape	1,3-Butadiene, acrylonitrile copolymer, 3-carbo	68891-46-3		0.080	mg	20000	721
				supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.080	mg	20000	721
				supplier	Bonding wire	Gold (Au)	7440-57-5		2.115	mg	1000000	19054
				supplier	Molding Compound	Silical (Fused)	60676-86-0,7631-86-9		50.860	mg	907000	458198
				supplier	Molding Compound	Epoxy resin	Trade Secret		2.804	mg	50000	25259
				supplier	Molding Compound	Phenol resin	Trade Secret		2.243	mg	40000	20207
				supplier	Molding Compound	Carbon Black	1333-86-4		0.168	mg	3000	1516
				supplier	Solder	Tin (Sn)	7440-31-5		4.717	mg	965000	42495
Solder balls (SN96.5 AG3.5%)	Solder	4.888	mg	supplier	Solder	Silver (Ag)	7440-22-4		0.171	mg	35000	1541